



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/038,264
Applicant : Seungbae Park et al.
Filed : January 3, 2002
TC/A.U. : 3679
Examiner : Ernesto Garcia

18/Amendment
CP
10-27-03

Docket No. : EN999048D
Title : SOLDER INTERCONNECT TECHNIQUES
Customer No. : 36458

SUPPLEMENTAL AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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S I R:

In response to the Office action of October 3, 2003, please amend the above-identified application as indicated. This amendment replaces in its entirety the amendment filed on September 8, 2003.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims begin on page 3 of this paper.

Amendments to the Drawings begin on page 6 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

Remarks/Arguments begin on page 7 of this paper.

An Appendix including amended drawing figures is attached following page 9 of this paper.

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